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Establishment of Singulation Technology Unrestricted by Package Shape

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TOWA CORPORATION hereby announces the establishment of a new singulation process that meets flexible cutting needs, expected to contribute to the expansion of semiconductor applications and production efficiency.

1. About the Technology

(1) Overview

The demand for diversified semiconductor packaging is increasing due to the expansion of semiconductor applications in AI, electric vehicles (EVs), and wearable devices, as well as efforts to reduce costs and improve productivity in semiconductor manufacturing processes. Additionally, as packaging needs diversify, cutting processes that can flexibly accommodate various shapes are required.

To address these process challenges, we have established singulation technology using lasers in collaboration with our subsidiary, TOWA LASERFRONT Corporation, operates a laser business.

This technology enables flexible chip arrangement on lead frames, contributing to cost reduction and productivity improvement in semiconductor manufacturing. Furthermore, by enabling the cutting of non-rectangular packages, which are uncommon in semiconductors, it enhances design flexibility, which in turn contributes to improved mounting efficiency and the expanded application of semiconductors.

Additionally, the dry laser cutting process eliminates 100% of water usage in the singulation process, significantly contributing to water usage reduction at customer facilities.

(2) Product to Which This Technology is Applied: "LSG1040" (Sales started in March 2025)

2. Future Outlook

We have already received approximately 20 inquiries over the next three years. As package cutting needs continue to diversify, we will strive to expand our share in the singulation equipment market by consistently offering optimal process solutions.